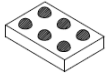


# MECHANICAL CASE OUTLINE

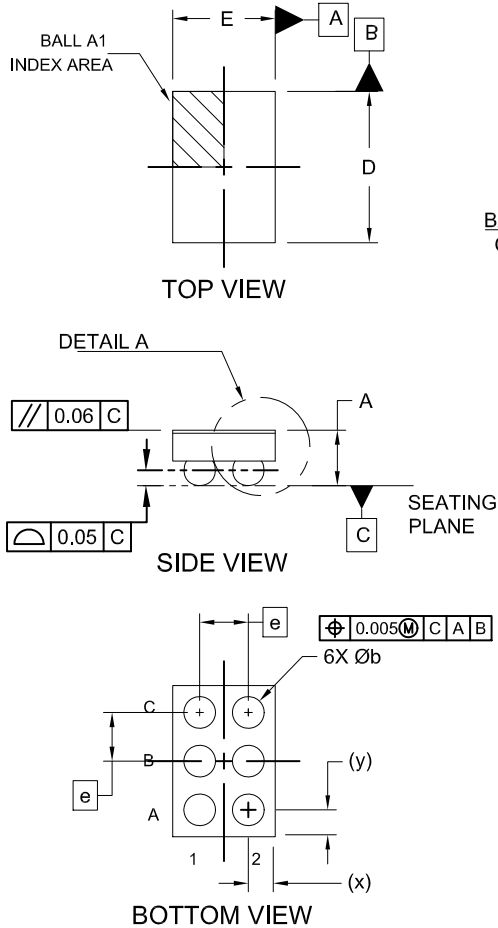
## PACKAGE DIMENSIONS

ON Semiconductor®



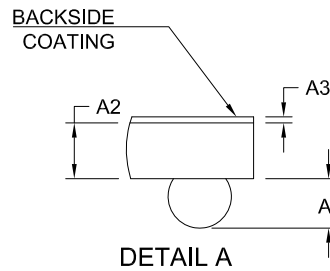
**WLCSP6 1.242x0.842x0.457**  
**CASE 567TS**  
**ISSUE A**

DATE 06 JUN 2019

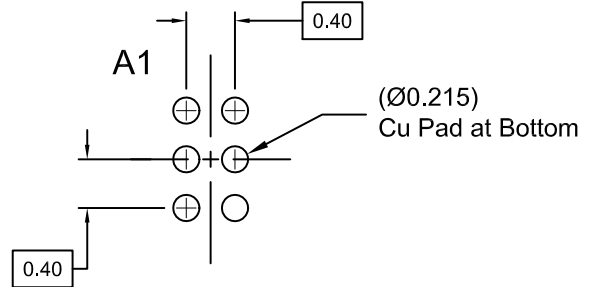


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.419	0.457	0.495
A1	0.183	0.203	0.223
A2	0.214	0.229	0.244
A3	0.022	0.025	0.028
b	0.24	0.26	0.28
D	1.212	1.242	1.272
E	0.812	0.842	0.872
e	0.40 BSC		
x	0.206	0.221	0.236
y	0.206	0.221	0.236



**RECOMMENDED MOUNTING FOOTPRINT\*  
 (NSMD PAD TYPE)**

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP6 1.242x0.842x0.457</b>	<b>PAGE 1 OF 1</b>

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